CHIPQUIK®

SMDSWLF.031 10Z

Datasheet revision 1.0 www.chipquik.com

Solder Wire SAC305 No-Clean with 2.2% Flux Core 1oz Spool

Product Highlights

2.2% flux core Made from grade-A virgin metals Smaller Size RoHS II and REACH compliant

Specifications

Alloy: Sn96.5/Ag3.0/Cu0.5

Wire Diameter: 0.031"
Flux Type: No-Clean
Flux Classification: ROL0

Melting Point: 217-220°C (423-428°F)

Packaging: 1 oz spool

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):

Yes
RoHS 2 Directive 2011/65/EU:

Yes